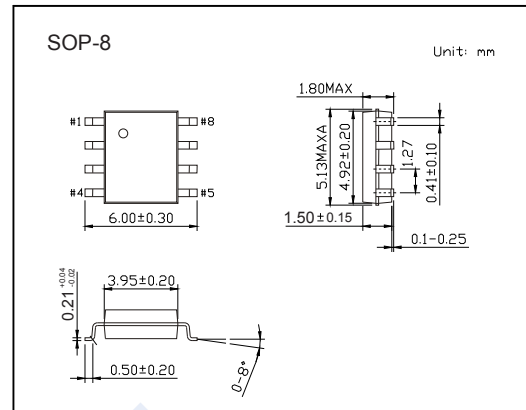
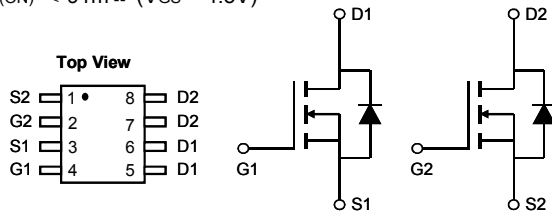


## N-Channel Enhancement MOSFET

### AO4886 (KO4886)

#### ■ Features

- $V_{DS} (V) = 100V$
- $I_D = 3.3A (V_{GS} = 10V)$
- $R_{DS(ON)} < 80m\Omega (V_{GS} = 10V)$
- $R_{DS(ON)} < 91m\Omega (V_{GS} = 4.5V)$



#### ■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current	$I_D$	$T_A=25^\circ C$	3.3
		$T_A=70^\circ C$	2.7
Pulsed Drain Current *1	$I_{DM}$	17	A
Avalanche Current *1	$I_{AS}, I_{AR}$	14	A
Avalanche Energy $L=0.1mH$ *1	$E_{AS}, E_{AR}$	10	mJ
Power Dissipation *2	$P_D$	$T_A=25^\circ C$	2
		$T_A=70^\circ C$	1.28
Thermal Resistance.Junction- to-Ambient *3	$R_{thJA}$	$t \leq 10S$	62.5
		Steady-State *4	90
Thermal Resistance.Junction- to-Case	$R_{thJC}$	40	$^\circ C/W$
Junction Temperature	$T_J$	150	
Storage Temperature Range	$T_{stg}$	-55 to 150	$^\circ C$

\*1 Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}=150^\circ C$ .

Ratings are based on low frequency and duty cycles to keep initial  $T_J=25^\circ C$ .

\*2 The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^\circ C$ , using  $\leq 10s$  junction-to-ambient thermal resistance.

\*3 The value of  $R_{qJA}$  is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ C$ .

\*4 The  $R_{qJA}$  is the sum of the thermal impedance from junction to lead  $R_{qJL}$  and lead to ambient.

## N-Channel Enhancement MOSFET

### AO4886 (KO4886)

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit	
Drain-Source Breakdown Voltage	V <sub>DSS</sub>	I <sub>D</sub> =250 μA, V <sub>GS</sub> =0V	100			V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V			1	μA	
		V <sub>DS</sub> =100V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C			5		
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA	1.6	2.2	2.7	V	
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =3A		63.5	80	mΩ	
		V <sub>GS</sub> =10V, I <sub>D</sub> =3A, T <sub>J</sub> =125°C		122	152		
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A		70	91		
On State Drain Current	I <sub>D(ON)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =5V	17			A	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =3A		20		S	
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =50V, f=1MHz	620	778	942	pF	
Output Capacitance	C <sub>oss</sub>		38	55	81		
Reverse Transfer Capacitance	C <sub>rss</sub>		13	24	35		
Gate Resistance	R <sub>g</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz	0.7	1.45	2.2	Ω	
Total Gate Charge (10V)	Q <sub>g</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =50V, I <sub>D</sub> =3A	13	16.3	20	nC	
Total Gate Charge (4.5V)			6.4	8.1	10		
Gate Source Charge			Q <sub>gs</sub>	2.2	2.8		3.4
Gate Drain Charge			Q <sub>gd</sub>	2.4	4.1		5.8
Turn-On DelayTime	t <sub>d(on)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =50V, R <sub>L</sub> =16.7 Ω, R <sub>GEN</sub> =3 Ω		6		ns	
Turn-On Rise Time	t <sub>r</sub>			2.5			
Turn-Off DelayTime	t <sub>d(off)</sub>			21			
Turn-Off Fall Time	t <sub>f</sub>			2.4			
Body Diode Reverse Recovery Time	t <sub>rr</sub>		I <sub>F</sub> = 3A, di/dt= 500A/μs	14	21		28
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 3A, di/dt= 500A/μs	65	94	123	nC	
Maximum Body-Diode Continuous Current	I <sub>S</sub>				2.5	A	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =1A, V <sub>GS</sub> =0V		0.74	1	V	

■ Marking

Marking	4886
	KA****

## N-Channel Enhancement MOSFET

### AO4886 (KO4886)

■ Typical Characteristics

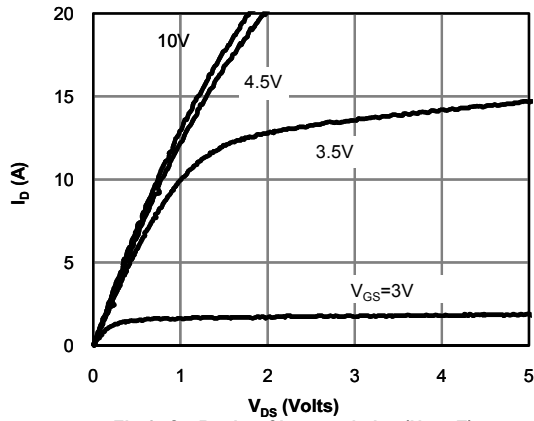


Fig 1: On-Region Characteristics (Note E)

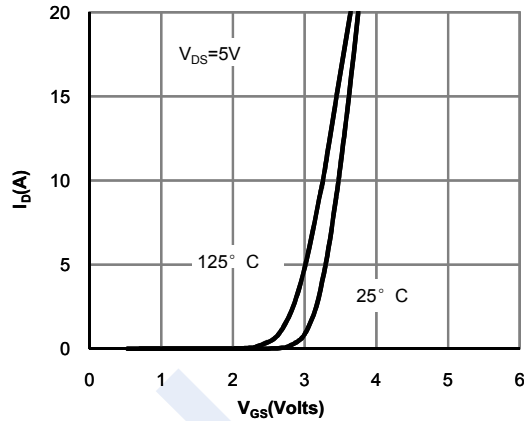


Figure 2: Transfer Characteristics (Note E)

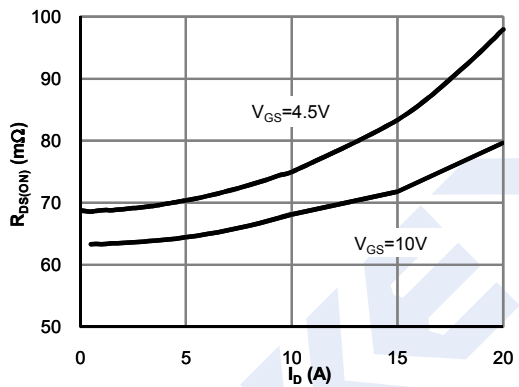


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

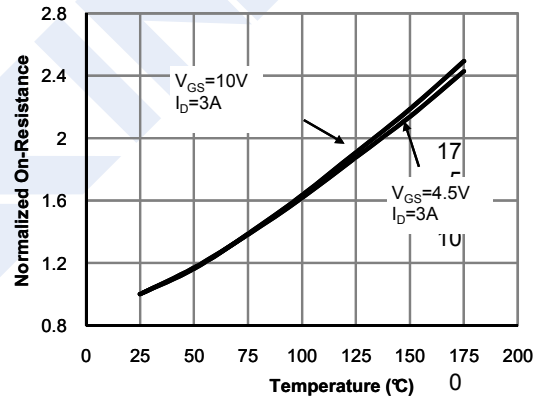


Figure 4: On-Resistance vs. Junction Temperature (Note E)

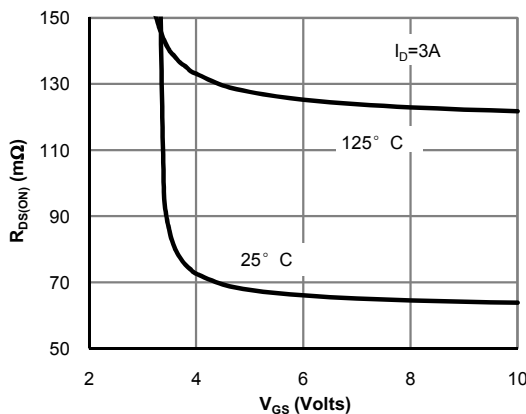


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

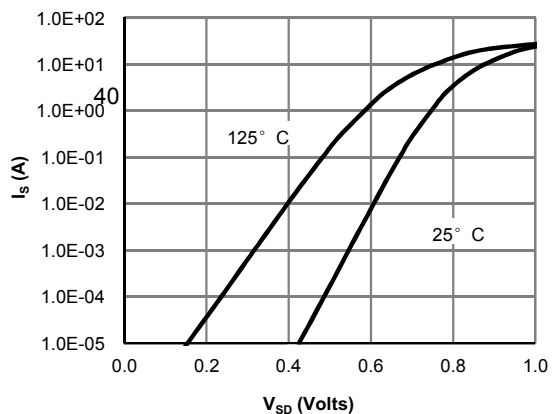


Figure 6: Body-Diode Characteristics (Note E)

## N-Channel Enhancement MOSFET

### AO4886 (KO4886)

#### ■ Typical Characteristics

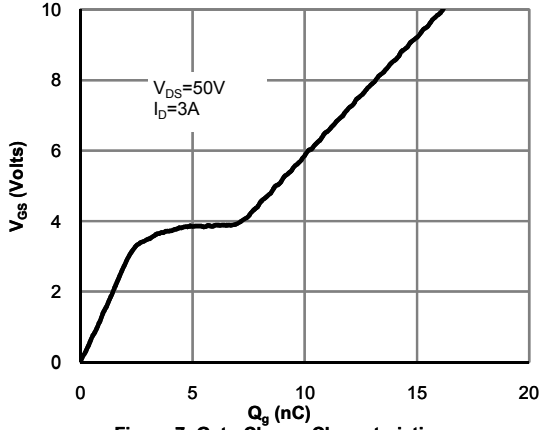


Figure 7: Gate-Charge Characteristics

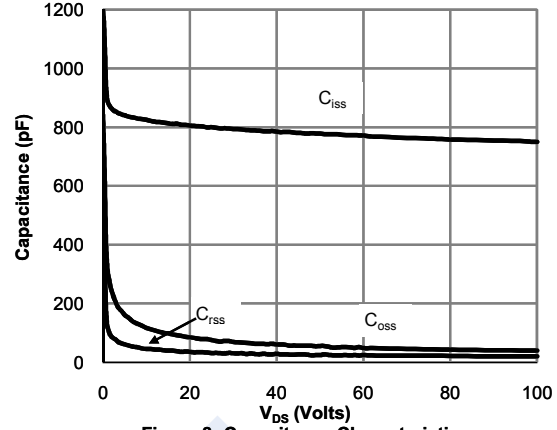


Figure 8: Capacitance Characteristics

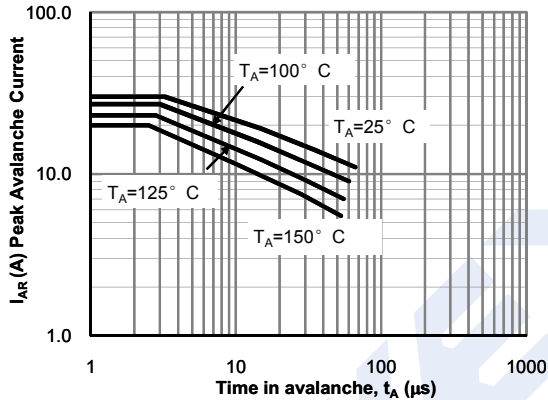


Figure 9: Single Pulse Avalanche capability (Note C)

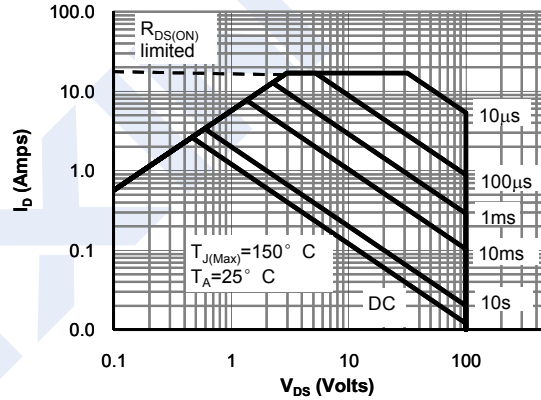


Figure 10: Maximum Forward Biased Safe Operating Area (Note F)

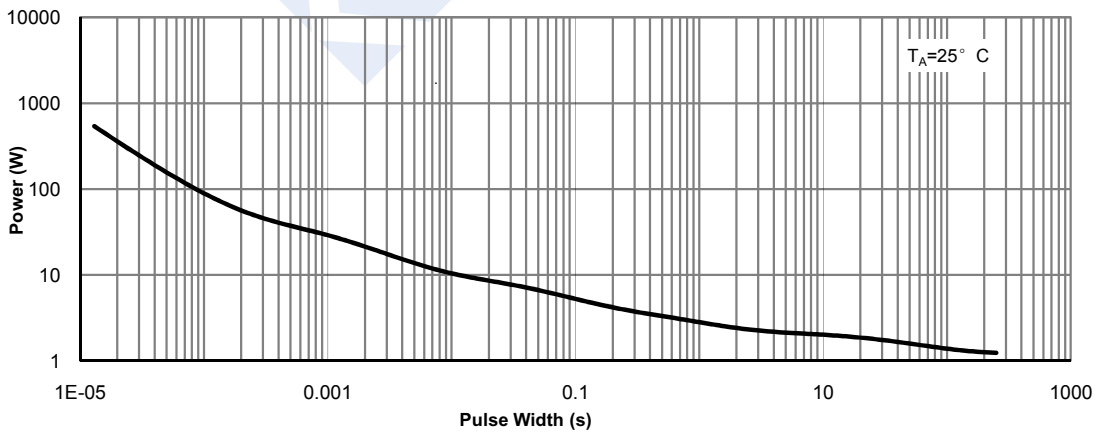


Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note F)

## N-Channel Enhancement MOSFET AO4886 (KO4886)

■ Typical Characteristics

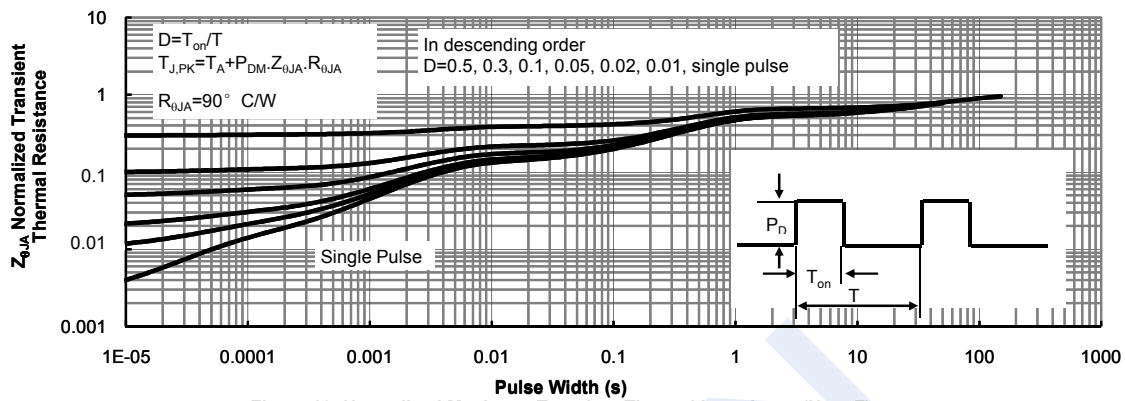


Figure 12: Normalized Maximum Transient Thermal Impedance (Note F)